

SLOTTED SUBSTRATES AND METHODS AND SYSTEMS FOR FORMING SAME

ABSTRACT

5 Methods and systems for forming slots (604) in a substrate (606) that has
opposing first and second surfaces. The method makes a laser cut through either
the first surface (610) or second surface (612) of the substrate (606) sufficient to
form a first trench (802). Material is also removed through the other of the first
and second surfaces effective to form, in combination with the laser cut, a slot
10 (604). At least a portion of the slot (604) passes entirely through the substrate
(606), and the slot (604) has an aspect ratio greater than or equal to 1.

(FIG. 6)

